



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

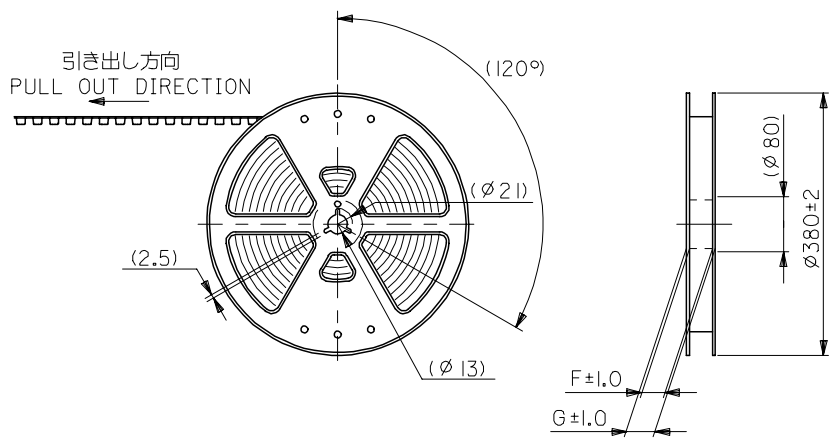
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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

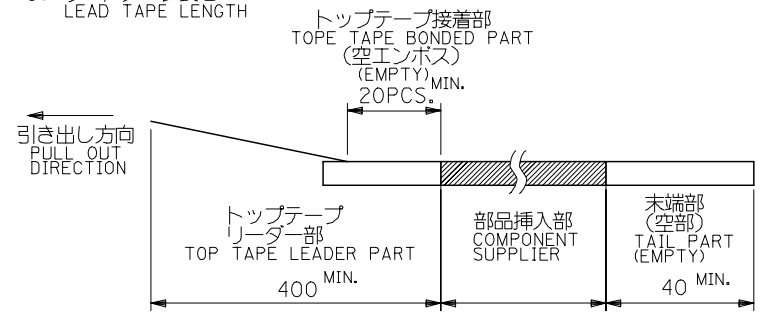


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注)
NOTES

- 製品番号54363-**81 詳細寸法については、製品単体図面を参照下さい。
IN THE PACKAGE PART NUMBER 54363-**81 DETAILED DIMENSIONS, SEE SALES DRAWING FOR CONNECTOR.
- 梱包数量：2500個/リール
NUMBER OF CONNECTORS:2500 PCS/REEL.
- リードテープ長さ
LEAD TAPE LENGTH



- 材料
MATERIAL
キャリアテープ：ポリプロピレン (PP)
CARRIER TAPE:POLYPROPYLENE(PP)
トップテープ：PET, PE, PEF
TOP TAPE:PET,PE,PEF
リール：ポリスチレン
REEL : POLYSTYRENE

61.4	57.4	56±0.3	52.4	44.2	26.2	40.55	54363-1689	160	—	
				39.2		35.55	54363-1489	140	○	
49.4	45.4	44±0.3	40.4	31.7	20.2	28.05	54363-1189	110	○	
				29.2		25.55	54363-1089	100	○	
				26.7		23.05	54363-0989	90	—	
37.4	33.4	32±0.3	28.4	24.2	14.2	20.55	54363-0889	80	○	
				21.7		18.05	54363-0789	70	○	
				19.2		15.55	54363-0689	60	○	
29.4	25.4	24±0.3	—	16.7	11.5	13.05	54363-0589	50	○	
				14.2		10.55	54363-0489	40	○	
				11.7		8.05	54363-0389	30	○	
21.4	17.4	16±0.3	—	9.2	7.5	5.55	54363-0289	20	○	
G	F	E キャリアテープ幅 CARRIER TAPE WIDTH		D	(C)	(B)	(A)	製品番号 MATERIAL NO.	極数 CIRCUITS	量産対応 AVAILABLE

REVISED EC NO: J2007-1632 DRWN: NABEI 2006/12/05 CHKDK: TOYODA 2006/12/06 APPR: NUKITA 2006/12/07	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	±0.2	DRAWN BY Y. AOYAGI	DATE 2006/11/08	TITLE EMBOSSD TAPE PACKAGE FOR 54363-**81			
		10 OVER 30 UNDER	±0.25	CHECKED BY K. TOYODA	DATE 2006/11/08				
		30 OVER	±0.3	APPROVED BY N. UKITA	DATE 2006/11/08	MOLEX INCORPORATED			
		ANGULAR	±3 °	MATERIAL NO.	DOCUMENT NO.	SEE CHART		SD-54363-049	SHEET NO. 1 OF 2
A	REV	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

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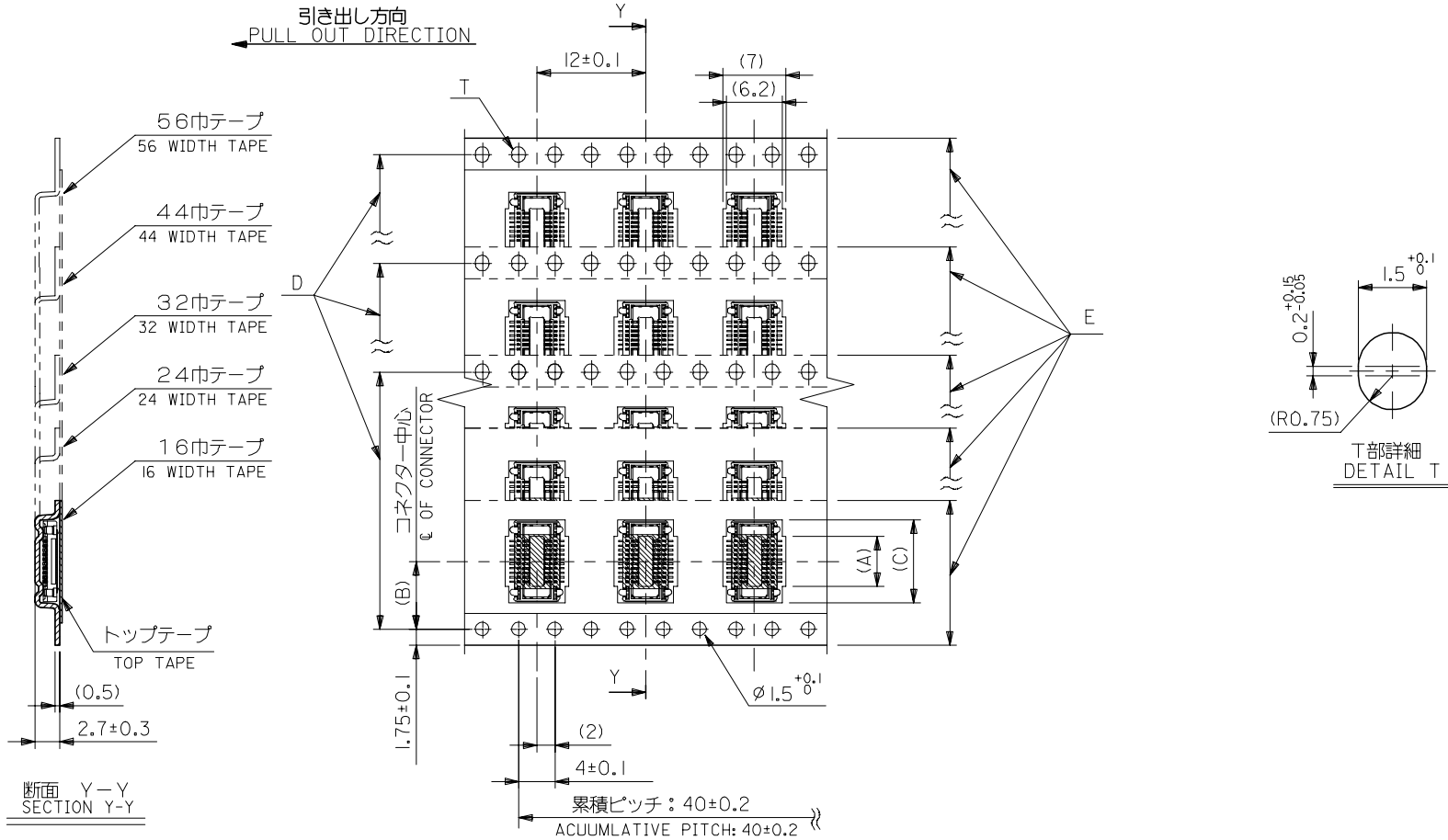
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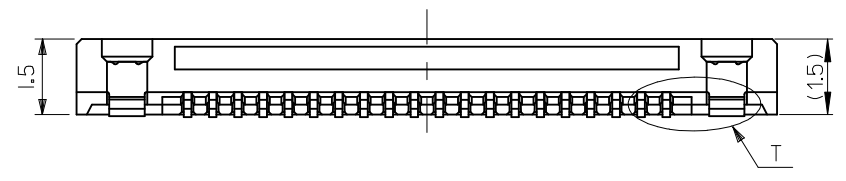
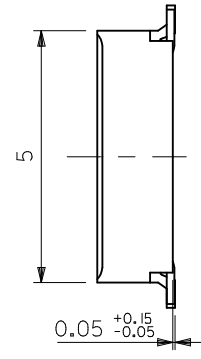
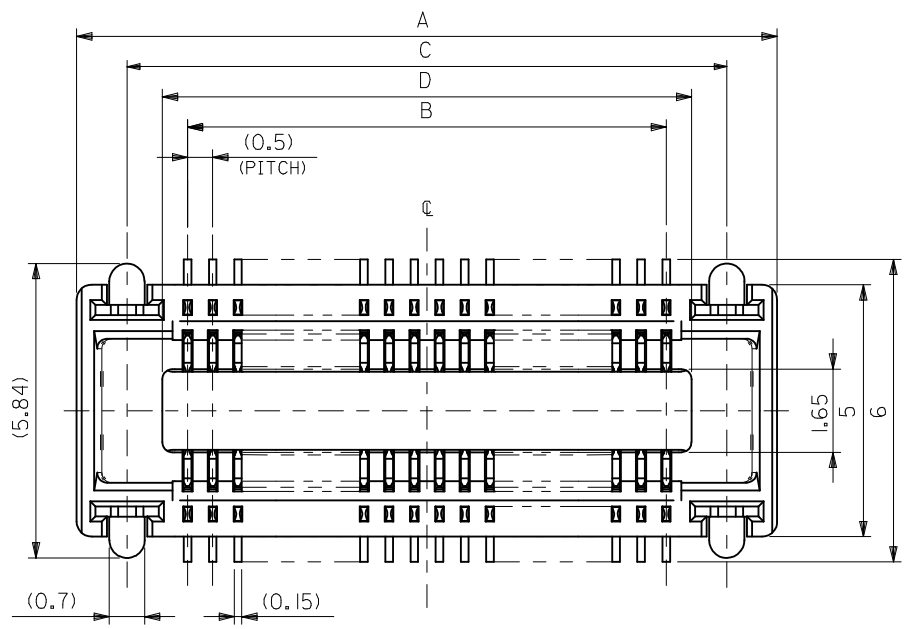
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B

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REVISED EC NO: J2007-1632 DRWN: MABEI CHKDK: TOYODA APPR: NUKITA 2006/12/05 2006/12/06 2006/12/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY Y. AOYAGI	DATE 2006/11/08	TITLE EMBOSSD TAPE PACKAGE FOR 54363-**81			
	10 OVER 30 UNDER	±0.25	CHECKED BY K. TOYODA	DATE 2006/11/08	MOLEX INCORPORATED DOCUMENT NO. SD-54363-049 SHEET NO. 2 OF 2			
	30 OVER	±0.3	APPROVED BY N. UKITA	DATE 2006/11/08				
	ANGULAR	±3 °	MATERIAL NO.		SEE SHEET 1			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				



注記
NOTES:

1. 材質
MATERIAL
ハウジング: LCP (液晶ポリマー)、ガラス充填、黒色、UL 94V-0
HOUSING: LCP (LIQUID CRYSTAL POLYMER), GLASS FILLED, BLACK, UL 94V-0
ターミナル: 銅合金 (t=0.15)
TERMINAL: COPPER ALLOY (t=0.15)
ネイル: 銅合金 (t=0.2)
NAIL: COPPER ALLOY (t=0.2)
2. メッキ仕様
PLATING
ターミナル
TERMINAL
接点部: 金メッキ 0.25マイクロメートル以上
CONTACT AREA: GOLD 0.25 MICROMETER MINIMUM
半田付け部: 金メッキ 0.4マイクロメートル以上
SOLDER TAIL AREA: GOLD 0.4 MICROMETER MAXIMUM
下地メッキ: ニッケルメッキ 1.5マイクロメートル以上
UNDER PLATING: NICKEL 1.5 MICROMETER MINIMUM
ネイル
NAIL
錫メッキ 3.0マイクロメートル以上
TIN 3.0 MICROMETER MINIMUM
下地メッキ: ニッケルメッキ 1.0マイクロメートル以上
UNDER PLATING: NICKEL 1.0 MICROMETER MINIMUM
3. テール平坦度は、0.08ミリメートル以下。テールとネイルを併せた平坦度は、0.1ミリメートル以下。
TAIL COPLANARITY TO BE 0.08 MAXIMUM. TAILS AND NAILS COPLANARITY TO BE 0.1 MAXIMUM.
4. 嵌合相手: 55201-****、55650-**** (H=2mm)
MATED CONN.: 55201-****, 55650-**** (H=2mm)
5. 本製品は、54363-**71(エンボス梱包品 54363-**78)のニッケルバリア品である。
THIS PRODUCT IS 'NICKEL BARRIER' OF 54363-**71(EMBOSSED TAPE PKG 54363-**78).

40.5	41.9	39.5	43.9	54363-1689	54363-1681	160	—
35.5	36.9	34.5	38.9	54363-1489	54363-1481	140	○
30.5	31.9	29.5	33.9	54363-1289	54363-1281	120	○
28	29.4	27	31.4	54363-1189	54363-1181	110	○
25.5	26.9	24.5	28.9	54363-1089	54363-1081	100	○
23	24.4	22	26.4	54363-0989	54363-0981	90	—
20.5	21.9	19.5	23.9	54363-0889	54363-0881	80	○
18	19.4	17	21.4	54363-0789	54363-0781	70	○
15.5	16.9	14.5	18.9	54363-0689	54363-0681	60	○
13	14.4	12	16.4	54363-0589	54363-0581	50	○
10.5	11.9	9.5	13.9	54363-0489	54363-0481	40	○
8	9.4	7	11.4	54363-0389	54363-0381	30	○
5.5	6.9	4.5	8.9	54363-0289	54363-0281	20	○
D	C	B	A	エンボス梱包品 EMBOSSED TAPE PACKAGING	製品番号 MATERIAL NO.	極数 CIRCUITS	量産対応 AVAILABLE

REVISED EC NO: J2016-0601 DRWN: JFURUKAWA 2015/12/08 CHKD: TASAKAWA 2015/12/08 APPR: KMORIKAWA 2015/12/16	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	UNDER	±0.03	DRAWN BY	DATE	TITLE	
	0.25 OVER	0.5 UNDER	±0.05	Y. AOYAGI	2006/11/08	0.5 MM PITCH B/B CONN. WITH FITTING NAIL -LEAD FREE-	
	0.5 OVER	1.0 UNDER	±0.1	K. TOYODA	2006/11/08	molex	
	1.0 OVER	30 UNDER	±0.2	N. UKITA	2006/11/08		
30 OVER		±0.3	MATERIAL NO.		DOCUMENT NO.	SHEET NO.	
ANGULAR	±3 °		SEE CHART		SD-54363-050	1 OF 2	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

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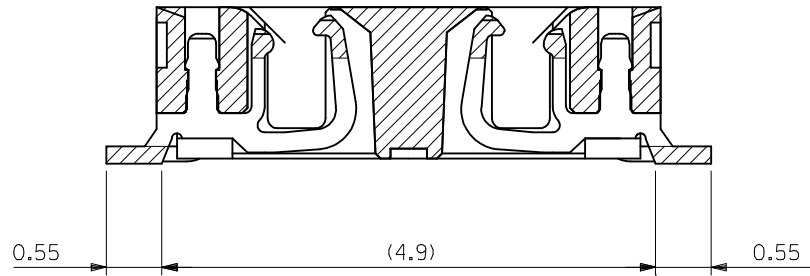
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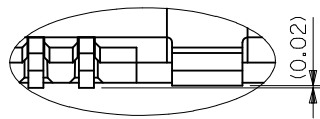
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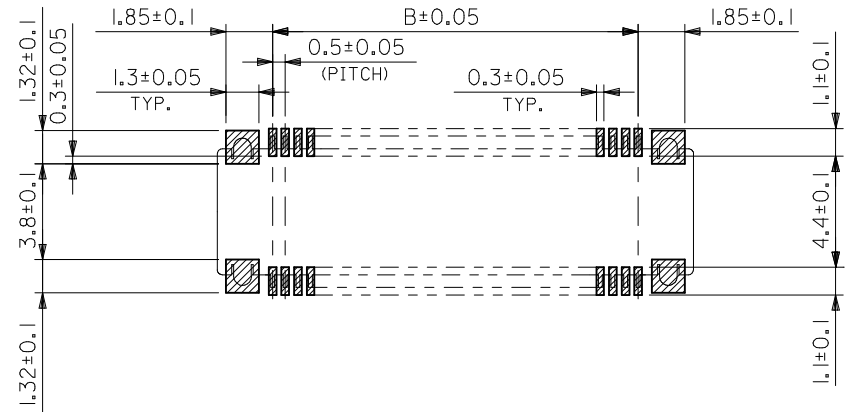
A



半田付け部詳細図
DETAIL FOR SOLDERING AREA



上部詳細
DETAIL T



推奨基板寸法
RECOMMENDED PCB PATTERN LAYOUT
(SCALE 5:1)

REVISED EC NO: J2016-0601 DRWN: JFURUKAWA 2015/12/08 CHK'D: TASAKAWA 2015/12/08 APPR: KMORIKAWA 2015/12/16	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	UNDER	±0.03	DRAWN BY	DATE	TITLE		
	0.25 OVER	0.5 UNDER	±0.05	Y. AOYAGI	2006/11/08	0.5 MM PITCH B/B CONN. WITH FITTING NAIL -LEAD FREE-		
	0.5 OVER	1.0 UNDER	±0.1	CHECKED BY	DATE			
	1.0 OVER	30 UNDER	±0.2	K. TOYODA	2006/11/08	molex DOCUMENT NO. SD-54363-050 SHEET NO. 2 OF 2		
	10 OVER	30 UNDER	±0.25	APPROVED BY	DATE			
30 OVER		±0.3	N. UKITA	2006/11/08				
ANGULAR	±3 °		MATERIAL NO. SEE SHEET 1					
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

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